

## ABSTRACT OF THE DISCLOSURE

A package for a semiconductor die comprises a semiconductor die with a bond pad. The package further includes a package lead and a bond wire with a first end portion coupled to the package lead, a second end portion coupled to the bond pad, and an intermediate portion. A non-conductive intermediate lead finger mounting substrate with an intermediate lead finger is positioned within the package. The intermediate lead finger is positioned between the lead finger and the bond pad and is attached to the intermediate portion of the bond wire.

Patent 2009/0123456